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#### 100V P-CHANNEL ENHANCEMENT MODE MOSFET

#### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> T <sub>A</sub> = +25°C
-100V	350mΩ @ V <sub>GS</sub> = -10V	-2.4A
	450mΩ @ V <sub>GS</sub> = -6V	-2.1A

# Features and Benefits

- Fast Switching Speed
- Low Input Capacitance
- Low Gate Drive
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

### **Description and Applications**

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- DC-DC Converters
- Power Management Functions
- Relay and Solenoid Driving

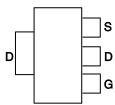
#### **Mechanical Data**

- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe;
  Solderable per MIL-STD-202, Method 208 <sup>(3)</sup>
- Weight: 0.112 grams (Approximate)

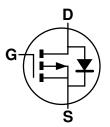
#### SOT223



Top View



Pin Out - Top View



**Equivalent Circuit** 

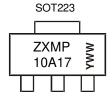
### **Ordering Information** (Note 5)

Part Number	Case	Packaging
ZXMP10A17GQTA	SOT223	1,000/Tape & Reel
ZXMP10A17GQTC	SOT223	4,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product\_compliance\_definitions.html.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## Marking Information



ZXMP10A17 = Product Type Marking Code YWW = Date Code Marking Y = Year (ex: 7 = 2017) WW = Week (01 to 53)



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage		$V_{DSS}$	-100	V	
Gate-Source Voltage		$V_{GS}$	±20	V	
		(Note 7)		-2.4	
Continuous Drain Current	$V_{GS} = -10V$	$T_A = +70^{\circ}C \text{ (Note 7)}$	$I_{D}$	-1.9	Α
		(Note 6)		-1.7	
Pulsed Drain Current	$V_{GS} = -10V$	(Note 8)	$I_{DM}$	-9.4	Α
Continuous Source Current (	Body Diode)	(Note 7)	Is	-4.5	Α
Pulsed Source Current (Body Diode) (Note 8)		I <sub>SM</sub>	-9.4	А	

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Power Dissipation	(Note 6)		2.0 16	W mW/°C	
Linear Derating Factor	(Note 7)	P <sub>D</sub>	3.9 31		
Thermal Resistance, Junction to Ambient	(Note 6)	D	62.5		
Thermal Resistance, Junction to Ambient	(Note 7)	$R_{\theta JA}$	32.0	°C/W	
Thermal Resistance, Junction to Case	(Note 6)	$R_{ hetaJC}$	7.7		
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

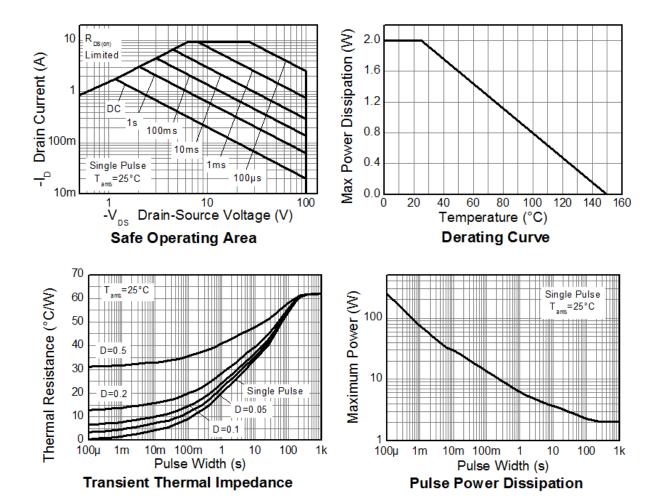
Characteristic	Symbol	Min	Тур	Max	Unit	Test C	ondition
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-100	_	_	V	$I_D = -250 \mu A, V_{GS} = 0 V$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-0.5	μΑ	$V_{DS} = -100V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS	•				•	•	
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-2.0	_	-4.0	V	$I_D = -250 \mu A, V_{DS} = V_{GS}$	
Chatia Dunin Causaa On Basistanaa (Nlata O)				0.350	Ω	V <sub>GS</sub> = -10V, I <sub>D</sub> =	-1.4A
Static Drain-Source On-Resistance (Note 9)	R <sub>DS(ON)</sub>	_		0.450	Ω	$V_{GS} = -6V$ , $I_D = -6V$	-1.2A
Forward Transconductance (Notes 9 & 10)	<b>g</b> fs	_	2.8	_	S	V <sub>DS</sub> = -15V, I <sub>D</sub> =	-1.4A
Diode Forward Voltage (Note 9)	$V_{SD}$	_	-0.85	-0.95	V	I <sub>S</sub> = -1.7A, V <sub>GS</sub> = 0V	
Reverse Recovery Time (Note 10)	t <sub>RR</sub>		33	_	ns	I <sub>F</sub> = -1.5A, di/dt = 100A/μs	
Reverse Recovery Charge (Note 10)	Q <sub>RR</sub>	_	48	_	nC		
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C <sub>iss</sub>		424	_	pF	.,	0) /
Output Capacitance	Coss	_	36.6	_	pF	$V_{DS} = -50V, V_{GS} = 0V$ - f = 1MHz	
Reverse Transfer Capacitance	$C_{rss}$	_	29.8	_	pF		
Total Gate Charge (Note 11)	$Q_g$	_	7.1	_	nC	$V_{GS} = -6.0V$	
Total Gate Charge (Note 11)	$Q_g$	_	10.7	_	nC		$V_{DS} = -50V$
Gate-Source Charge (Note 11)	$Q_{gs}$	_	1.7	_	nC	$V_{GS} = -10V$	$I_D = -1.4A$
Gate-Drain Charge (Note 11)	$Q_{gd}$	_	3.8	_	nC	1	
Turn-On Delay Time (Note 11)	t <sub>D(ON)</sub>	_	3.0	—	ns	$V_{DD} = -15V, V_{GS} = -10V$ $I_D = -1A, R_G \cong 6.0\Omega$	
Turn-On Rise Time (Note 11)	t <sub>R</sub>	_	3.5	—	ns		
Turn-Off Delay Time (Note 11)	t <sub>D(OFF)</sub>	_	13.4	—	ns		
Turn-Off Fall Time (Note 11)	t <sub>F</sub>	_	7.2		ns		

Notes:

- 6. For a device surface mounted on 25mm x 25mm x 1.6mm FR-4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 7. Same as Note 6, except the device is measured at  $t \le 10$  seconds.
- 8. Same as Note 6, except the device is pulsed with D = 0.02 and pulse width 300μs. The pulse current is limited by the maximum junction temperature.
- 9. Measured under pulsed conditions. Pulse width  $\leq 300 \mu s;$  duty cycle  $\leq 2\%.$
- 10. For design aid only, not subject to production testing.11. Switching characteristics are independent of operating junction temperatures.

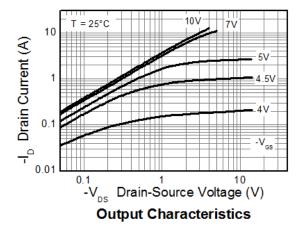


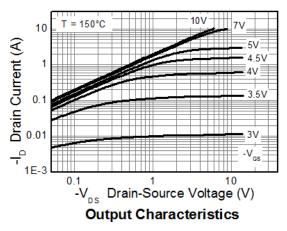
### **Thermal Characteristics**

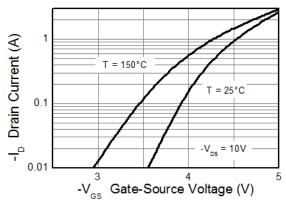


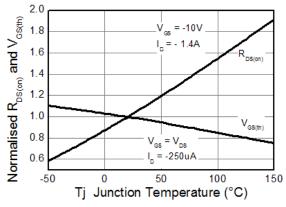


### **Typical Characteristics** (Cont.)



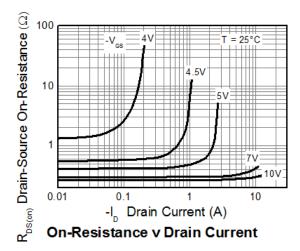


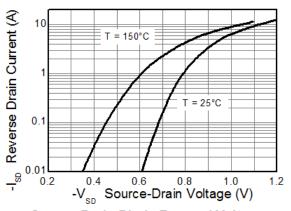




**Typical Transfer Characteristics** 

Normalised Curves v Temperature





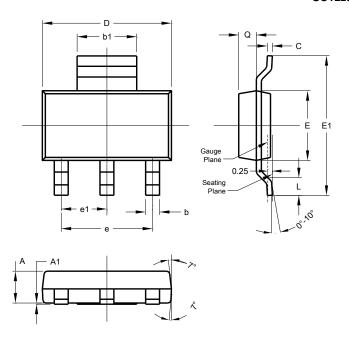
Source-Drain Diode Forward Voltage



### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT223

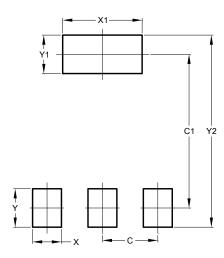


SOT223					
Dim	Min	Max	Тур		
Α	1.55	1.65	1.60		
<b>A</b> 1	0.010	0.15	0.05		
b	0.60	0.80	0.70		
b1	2.90	3.10	3.00		
C	0.20	0.30	0.25		
D	6.45	6.55	6.50		
Е	3.45	3.55	3.50		
E1	6.90	7.10	7.00		
е	-	-	4.60		
e1	-	-	2.30		
L	0.85	1.05	0.95		
Q	0.84	0.94	0.89		
All Dimensions in mm					

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **SOT223**



Dimensions	Value (in mm)
С	2.30
C1	6.40
Х	1.20
X1	3.30
Υ	1.60
Y1	1.60
٧o	8 00



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